dynamic viscoelasticity measuring instrument (manufactured by UBM Co., Ltd., Rheogel-E4000 type) with a chuck distance of 20 mm. The dynamic viscoelasticity of the test piece was measured under the conditions of tensile mode, a heating rate of 3°C/min, a temperature range of 30°C to 200°C, under air, a frequency of 10 Hz (constant), a sine wave, continuous vibration, and an initial load under manual control. From the measurement results, the temperature at which the Tan δ value of the uncured resin layer containing an epoxy resin showed the maximum value was determined as the glass transition temperature.

[0038] Peel Test

A 90° peel test was performed in which a laminated film containing a thermocompression bonding layer, or a laminate composed of an aluminum foil and a resin layer, was peeled off from the glass plate of each adhesive body by pulling in a direction of 90° with respect to the surface of the glass plate, and the 90° peel strength between the thermocompression bonding layer or the resin layer and the glass plate was measured. The tensile speed was 50 mm/min. The 90° peel test was performed under the conditions in which the temperature of the adhesive body was 25°C or 200°C, and the 90° peel strength at each temperature was determined.

[0039] 4. Heat Resistance

Examples A to E

Each of resin varnishes A, B, C, D, and E was applied to a support film that was peelable after drying. The coating film was dried by heating at 100°C for 10 minutes and at 300°C for 10 minutes to form a thermocompression bonding layer having a thickness of about 40 μm on

CLAIMS

[Claim 1]

A structure comprising:

a plurality of sheet-shaped glass substrates; and

an adhesive layer,

wherein the plurality of glass substrates are laminated in a thickness direction of the structure,

the adhesive layer is provided between adjacent glass substrates, and

at least a part of the adhesive layer is a film material having a first surface and a second surface on a back side thereof, the film material comprising one or more thermocompression bonding layers,

the thermocompression bonding layer is a resin layer that is non-adhesive at 25°C, has thermocompression bondability at a temperature 10°C or more higher than a glass transition temperature of the thermocompression bonding layer, and does not melt at 250°C or lower, and outermost layers on both the first surface side and the second surface side are the thermocompression bonding layers, and

the thermocompression bonding layer comprises a polyamideimide resin.

[Claim 2]

The structure according to claim 1, wherein a content of an organic solvent in the thermocompression bonding layer is less than 10 mass ppm based on a mass of the thermocompression bonding layer.

[Claim 3]

A wiring board comprising:

a plurality of sheet-shaped glass substrates;

an adhesive layer; and

a wiring layer,

wherein the plurality of glass substrates are laminated in a thickness direction of the wiring board,

the adhesive layer and the wiring layer are provided between adjacent glass substrates, and

at least a part of the adhesive layer is a film material having a first surface and a second surface on a back side thereof, the film material comprising one or more thermocompression bonding layers,

the thermocompression bonding layer is a resin layer that is non-adhesive at 25°C, has thermocompression bondability at a temperature 10°C or more higher than a glass transition temperature of the thermocompression bonding layer, and does not melt at 250°C or lower, and outermost layers on both the first surface side and the second surface side are the thermocompression bonding layers, and

the thermocompression bonding layer comprises a polyamideimide resin.

[Claim 4] The wiring board according to claim 4, wherein a content of an organic solvent in the thermocompression bonding layer is less than 10 mass ppm based on a mass of the thermocompression bonding layer.

[Claim 5] A method of producing the structure according to claim 1 or 2, the method comprising:

thermocompression bonding the film material to one of the plurality of the glass substrates, thereby providing the adhesive layer between the adjacent glass substrates.

[Claim 6] A method of producing the wiring board according to claim 1 or 2, the method comprising:

thermocompression bonding the film material to one of the plurality of the glass substrates, thereby providing the adhesive layer between the adjacent glass substrates.

[Claim 7] A film material having a first surface and a second surface on a back side thereof,

the film material comprising one or more thermocompression bonding layers,

wherein the thermocompression bonding layer is a resin layer that is non-adhesive at 25°C, has thermocompression bondability at a temperature 10°C or more higher than a glass transition temperature of the thermocompression bonding layer, and does not melt at 250°C or lower, and outermost layers on both the first surface side and the second surface side are the thermocompression bonding layers,

the thermocompression bonding layer comprises a polyamideimide resin, and

the film material is used as an adhesive layer in the structure according to claim 1 or 2.

[Claim 8] A film material having a first surface and a second surface on a back side thereof,

the film material comprising one or more thermocompression bonding layers,

wherein the thermocompression bonding layer is a resin layer that is non-adhesive at 25°C, has thermocompression bondability at a temperature 10°C or more higher than a glass transition temperature of the thermocompression bonding layer, and does not melt at 250°C or lower, and outermost layers on both the first surface side and the second surface side are the thermocompression bonding layers,

the thermocompression bonding layer comprises a polyamideimide resin, and

the film material is used as an adhesive layer in the wiring board according to claim 3 or 4.